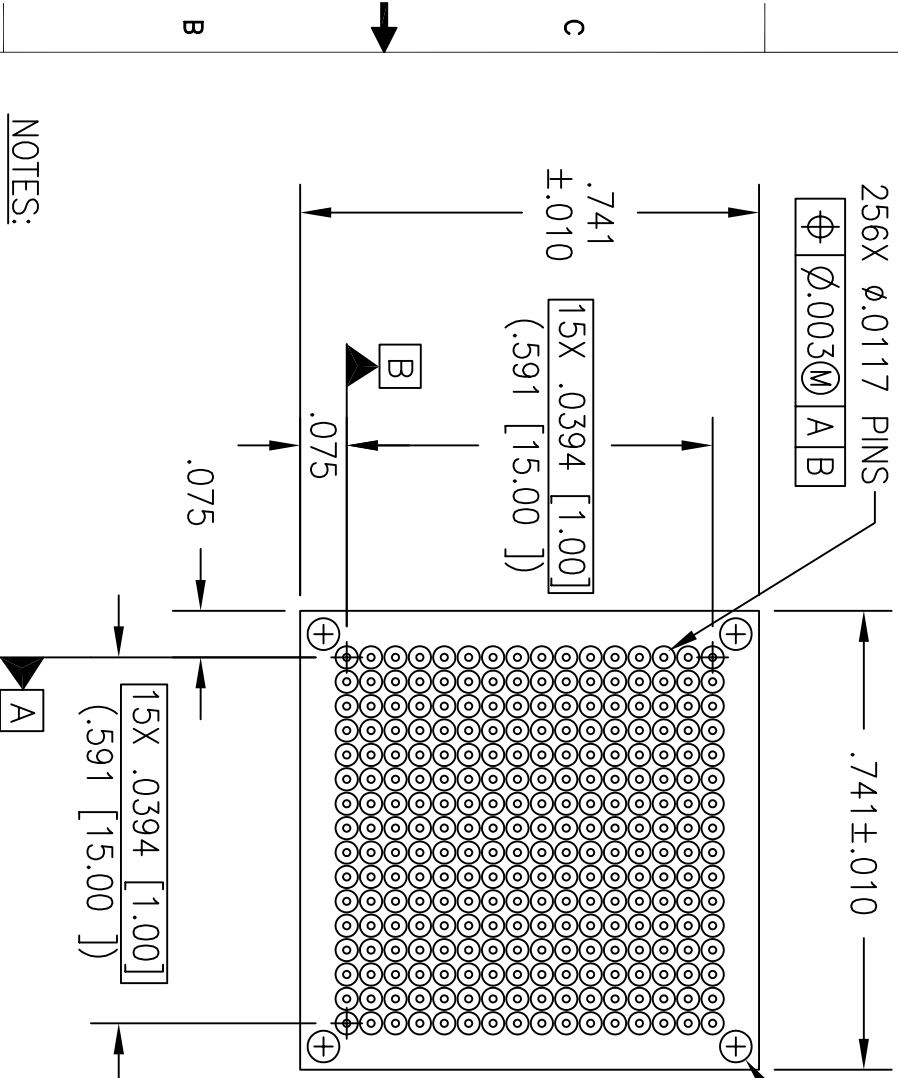


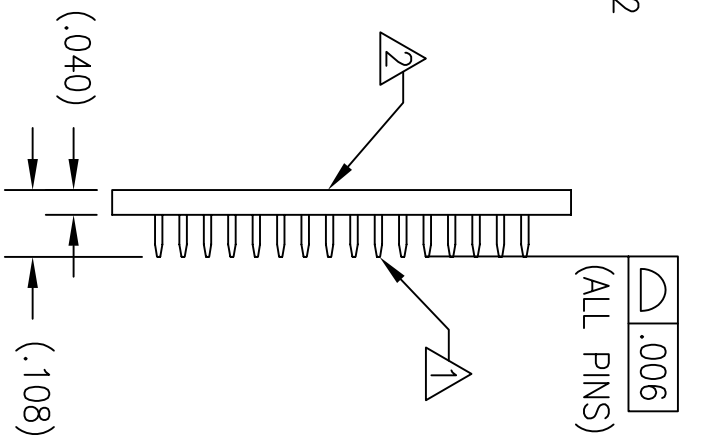
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REV	DESCRIPTION	EGN	DATE	APPROVAL
1	SALES RELEASE			


TOP VIEW



RS VIEW



- NOTES:
- PINS ϕ .01117
MATERIAL: PHOSPHOR BRONZE.
PLATING: HARD GOLD OVER NICKEL.
 - INSULATOR MATERIAL: FR4.

CONTRACT NO.		TITLE	
DRAWN BY	DATE	 INTERCONNECT SYSTEMS INC. 708 VIA ALONDRA, CAMARILLO, CA 93012	
DESIGNER	DATE	SIZE	
CHECKER	DATE	A	
PROCESS ENG.	DATE	HIL0-BGA PIN BASE	
		16 X 16, 256 PINS	
		1mm PITCH	
		SCALE	DRAWING NO.
		N/A	HLP-160256-B-10
		FINISHED ASST: HLP-160256-B-10	
		SHEET	1 OF 1

UNLESS OTHERWISE SPECIFIED:
 DIMENSIONS ARE IN INCHES
 TOLERANCES: ± 1/64
 ANGLES: ± .010
 DECIMALS: ± .005
 FRACTIONS: ± .0005

ASIZE 4 3 2 1